

74ABT241

Octal Buffer/Line Driver with 3-STATE Outputs

General Description

The ABT241 is an octal buffer and line driver with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus-oriented transmitter/receiver.

Features

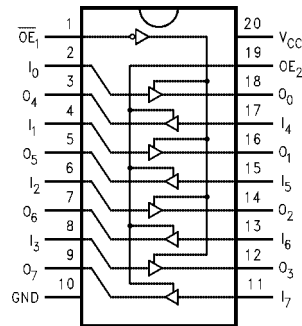
- Non-inverting buffers
- Output sink capability of 64 mA, source capability of 32 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT241CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
74ABT241CSJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT241CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74ABT241CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1$	Output Enable Input (Active LOW)
OE_2	Output Enable Input (Active HIGH)
I_0-I_7	Inputs
O_0-O_7	Outputs

Truth Table

$\overline{OE}_1$	I_{0-3}	O_{0-3}	$\overline{OE}_2$	I_{4-7}	O_{4-7}
H	X	Z	L	X	Z
L	H	H	H	H	H
L	L	L	H	L	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

Absolute Maximum Ratings(Note 1)

Storage Temperature	–65°C to +150°C
Ambient Temperature under Bias	–55°C to +125°C
Junction Temperature under Bias	–55°C to +150°C
V _{CC} Pin Potential to Ground Pin	–0.5V to +7.0V
Input Voltage (Note 2)	–0.5V to +7.0V
Input Current (Note 2)	–30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-Off State	–0.5V to 5.5V
in the HIGH State	–0.5V to V _{CC}
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
DC Latchup Source Current (Over Comm Operating Range)	–500 mA
Over Voltage Latchup (I/O)	10V

Recommended Operating Conditions

Free Air Ambient Temperature	–40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate ($\Delta V/\Delta t$)	
Data Input	50 mV/ns
Enable Input	20 mV/ns

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized LOW Signal
V _{CD}	Input Clamp Diode Voltage			–1.2	V	Min	I _{IN} = –18 mA
V _{OH}	Output HIGH Voltage	2.5			V	Min	I _{OH} = –3 mA
		2.0			V	Min	I _{OH} = –32 mA
V _{OL}	Output LOW Voltage			0.55	V	Min	I _{OL} = 64 mA
I _{IH}	Input HIGH Current			1	μA	Max	V _{IN} = 2.7V (Note 4)
				1	μA	Max	V _{IN} = V _{CC}
I _{BVI}	Input HIGH Current Breakdown Test			7	μA	Max	V _{IN} = 7.0V
I _{IL}	Input LOW Current			–1	μA	Max	V _{IN} = 0.5V (Note 4)
				–1	μA	Max	V _{IN} = 0.0V
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OZH}	Output Leakage Current			10	μA	0 – 5.5V	V _{OUT} = 2.7V; $\overline{OE_n}$ = 2.0V
I _{OZL}	Output Leakage Current			–10	μA	0 – 5.5V	V _{OUT} = 0.5V; $\overline{OE_n}$ = 2.0V
I _{OS}	Output Short-Circuit Current	–100		–275	mA	Max	V _{OUT} = 0.0V
I _{CEX}	Output High Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
I _{ZZ}	Bus Drainage Test			100	μA	0.0	V _{OUT} = 5.5V; All Others GND
I _{CCH}	Power Supply Current			50	μA	Max	All Outputs HIGH
I _{CCL}	Power Supply Current			30	mA	Max	All Outputs LOW
I _{CCZ}	Power Supply Current			50	μA	Max	$\overline{OE_n}$ = V _{CC} ; All Others at V _{CC} or Ground
I _{CCT}	Additional I _{CC} /Input	Outputs Enabled		2.5	mA	Max	V _I = V _{CC} – 2.1V
		Outputs 3-STATE		2.5	mA		Enable Input V _I = V _{CC} – 2.1V
		Outputs 3-STATE		50	μA		Data Input V _I = V _{CC} – 2.1V All Others at V _{CC} or Ground
I _{CCD}	Dynamic I _{CC} (Note 4)	No Load		0.1	mA/ MHz	Max	Outputs Open $\overline{OE_n}$ = GND, (Note 3) One Bit Toggling, 50% Duty Cycle

Note 3: For 8 bits toggling, I_{CCD} < 0.8 mA/MHz.

Note 4: Guaranteed, but not tested.

DC Electrical Characteristics

(SOIC package)

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions C _L = 50 pF, R _L = 500Ω
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}		0.5	0.8	V	5.0	T _A = 25°C (Note 5)
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-1.3	-0.8		V	5.0	T _A = 25°C (Note 5)
V _{OHV}	Minimum HIGH Level Dynamic Output Voltage	2.7	3.1		V	5.0	T _A = 25°C (Note 7)
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	2.0	1.5		V	5.0	T _A = 25°C (Note 6)
V _{ILD}	Maximum LOW Level Dynamic Input Voltage		1.1	0.8	V	5.0	T _A = 25°C (Note 6)

Note 5: Max number of outputs defined as (n). n – 1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.**Note 6:** Max number of data inputs (n) switching. n – 1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}). Guaranteed, but not tested.**Note 7:** Max number of outputs defined as (n). n – 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.**AC Electrical Characteristics**

(SOIC and SSOP package)

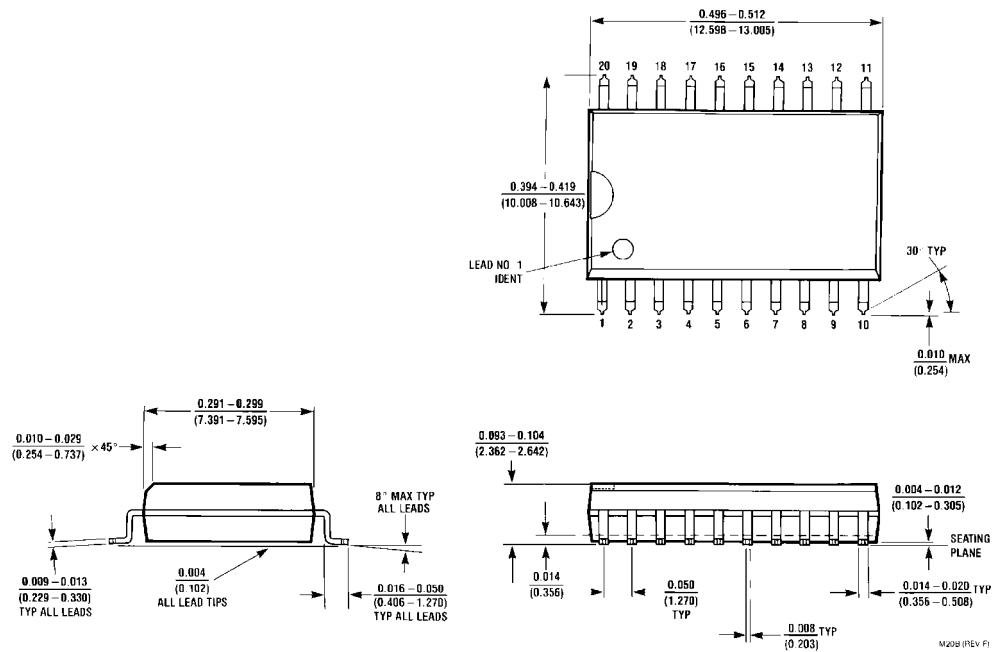
Symbol	Parameter	T _A = +25°C V _{CC} = +5V C _L = 50 pF			T _A = -40°C to +85°C V _{CC} = 4.5V–5.5V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay	1.0		4.6	1.0	4.6	ns
t _{PHL}	Data to Outputs	1.0		4.6	1.0	4.6	
t _{PZH}	Output Enable	1.1		6.8	1.1	6.8	ns
t _{PZL}	Time	1.3		6.8	1.3	6.8	
t _{PHZ}	Output Disable	1.6		6.8	1.6	6.8	ns
t _{PLZ}	Time	1.0		5.9	1.0	5.9	

Capacitance

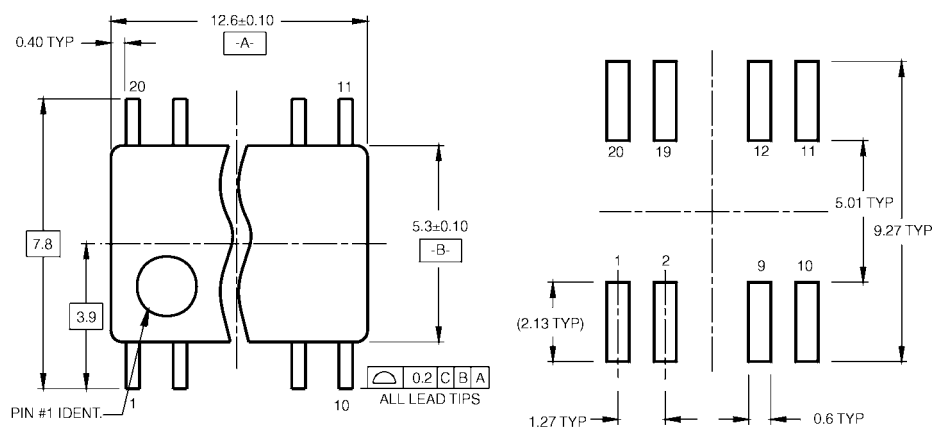
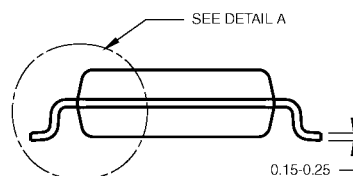
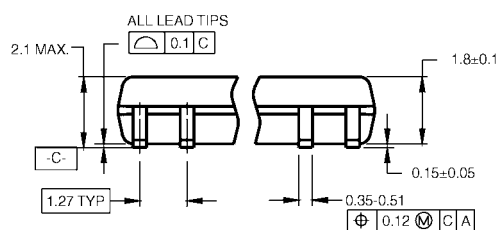
Symbol	Parameter	Typ	Units	Conditions T _A = 25°C
C _{IN}	Input Capacitance	5.0	pF	V _{CC} = 0V
C _{OUT} (Note 8)	Output Capacitance	9.0	pF	V _{CC} = 5.0V

Note 8: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
Package Number M20B

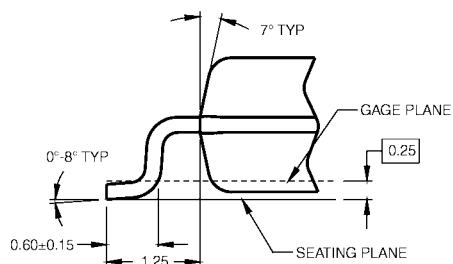
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

LAND PATTERN RECOMMENDATION


DIMENSIONS ARE IN MILLIMETERS

NOTES:

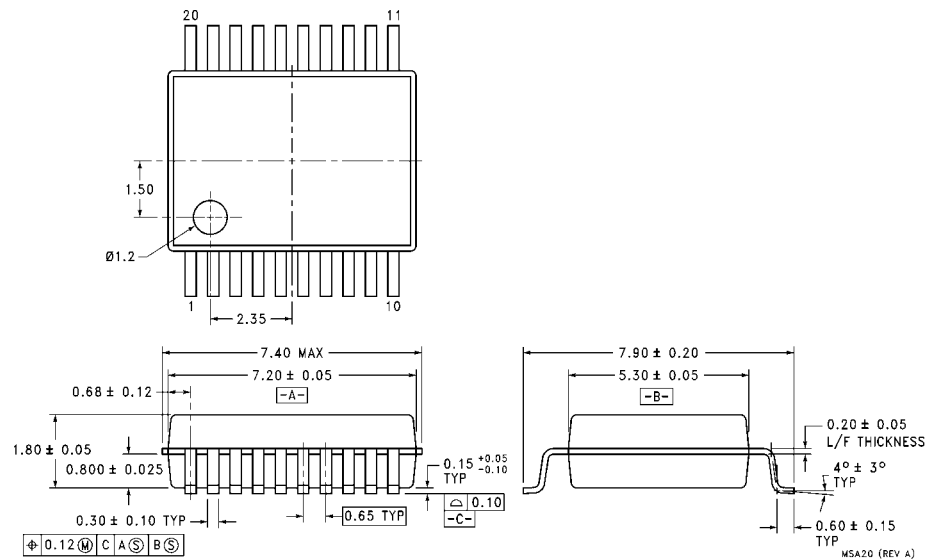
- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1


DETAIL A

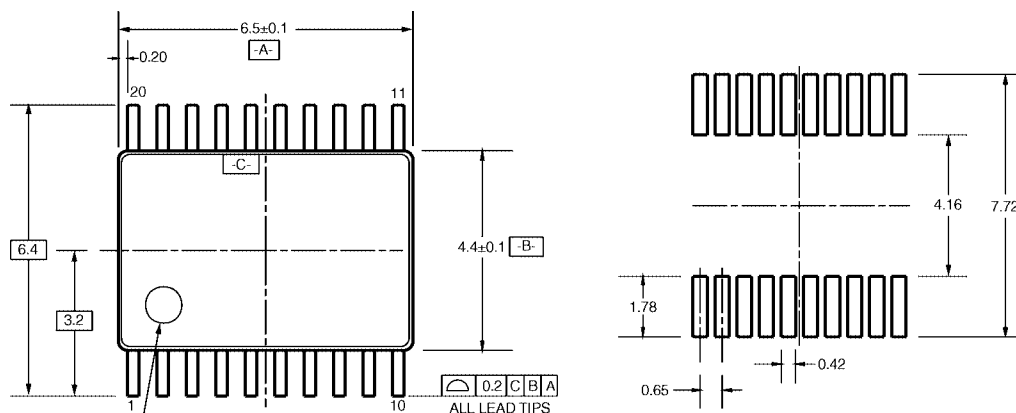
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

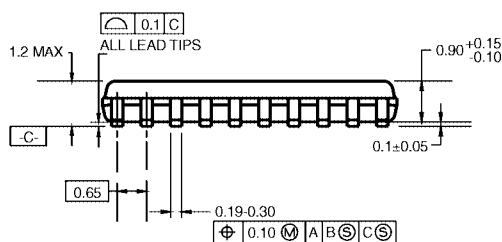


20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION

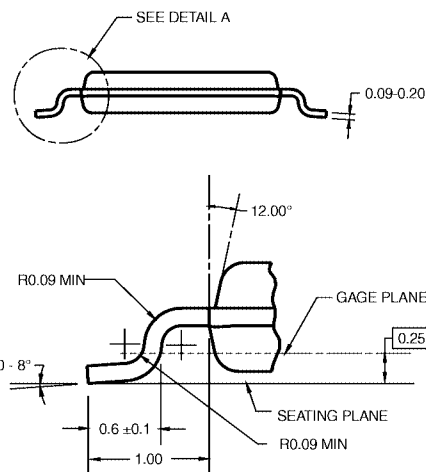


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20RevD1



DETAIL A

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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